

Title (en)

RESIN MOLDING MACHINE AND MEMBER FOR RESIN MOLDING MACHINE HAVING FILM IN PASSIVE STATE

Title (de)

HARZFORMMASCHINE UND GLIED FÜR HARZFORMMASCHINE MIT FILM IN PASSIVEM ZUSTAND

Title (fr)

MACHINE DE MOULAGE DE RESINE ET ELEMENT POUR MACHINE DE MOULAGE DE RESINE POSSEDANT UN FILM A L'ETAT PASSIF

Publication

EP 1607202 A4 20070801 (EN)

Application

EP 04714928 A 20040226

Priority

- JP 2004002263 W 20040226
- JP 2003055909 A 20030303

Abstract (en)

[origin: EP1607202A1] A member for a resin molding machine wherein it has a face contacting with a molten resin, and at least a part of the face is covered with a film of an oxide of a base material of the face or a component contained in the base material. The use of the member in the molding of a resin allows the prevention of the incorporation of a contaminant associated with the deterioration of a melt of the resin into a molded article from the resin. <IMAGE>

IPC 8 full level

B29C 33/38 (2006.01); **B29C 33/56** (2006.01); **B29C 45/17** (2006.01); **B29C 45/20** (2006.01); **B29C 45/37** (2006.01); **B29C 45/46** (2006.01); **C23C 8/10** (2006.01); **C23C 8/14** (2006.01); **C23C 8/18** (2006.01); **C23C 30/00** (2006.01); **B29K 23/00** (2006.01); **B29L 11/00** (2006.01)

CPC (source: EP US)

B29C 33/38 (2013.01 - EP US); **B29C 33/56** (2013.01 - EP US); **B29C 45/37** (2013.01 - EP US); **C23C 8/10** (2013.01 - EP US); **C23C 8/14** (2013.01 - EP US); **C23C 8/18** (2013.01 - EP US); **C23C 30/00** (2013.01 - EP US); **B29L 2031/3475** (2013.01 - EP US); **Y10S 425/808** (2013.01 - EP US)

Citation (search report)

- [X] GB 543767 A 19420312 - ERNEST WINDSOR BOWEN
- See references of WO 2004078447A1

Cited by

DE102006051308A1; US7901467B2; WO2008052662A3; TWI418654B

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EP 1607202 A1 20051221; **EP 1607202 A4 20070801**; JP 2004262133 A 20040924; JP 4185787 B2 20081126; US 2006193940 A1 20060831; US 7334769 B2 20080226; WO 2004078447 A1 20040916

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